EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S67	1	11/003369	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/09 16:17
S68	2	("20050275048").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/09 16:18
S69	2	("6791660").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/09 16:19
S70	2	("4565928").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/09 16:20
S72	761	(257/E21.237,E21.484).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/09 16:22
S73	54335	(photoelectric (image adj1 sensor)) and (grind $3 polish$3 thin$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:52
S75	894	S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:53
S74	894	(photoelectric (image adj1 sensor)) and ((grind $3 polish$3 thin$4) same ((glass dielectric) adj1 substrate)) and (glue adhesive (ultraviolet adj1 cured adj1 plastic) (epoxy adj1 resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:53

S77	2	((photoelectric (image adj1 sensor)) and ((grind$3 polish$3 thin$4) same ((glass dielectric) adj1 substrate)) and (glue adhesive (ultraviolet adj1 cured adj1 plastic) (epoxy adj1 resin))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:54
S76	1587	((photoelectric (image adj1 sensor)) and (grind$3 polish$3 thin$4)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:54
S78	3070	((257/E21.237,E21.484) or (438/118,456)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/03 16:48
S83	12443	S80 and S81 and S82	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S82	269667	(photoelectric (image adj1 sensor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S81	3251696	(grind$3 polish$3 thin$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S80	524017	(dielectric insulat$3 glass) near3 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S79	326450	(dielectric insulat$3) near3 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S84	306	(S80 and S81 and S82).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:50

S85	11	("4423435" | "5501989" | "5589694" | "5744822" | "5965064" | "6461890" | "6555917" | "6624921" | "6700133" | "7071488").PN. OR ("7180197").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/03 16:55
S86	2393	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/03 17:29
L1	2025783	semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:41
L4	21920	(substrate near3 L2).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:44
L3	44801	(substrate with L2).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:44
L2	3251696	(grind$3 polish$3 thin$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:44
L7	1581	L6 and L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:46
L6	182465	L5.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:46
L5	1657229	(glue adhesive (ultraviolet adj1 cured adj1 plastic) (epoxy adj1 resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:46
L10	192	L9 and L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:47

L9	139673	L8.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:47
L8	1900575	semiconductor adj chip integrated adj circuit IC	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:47
L11	39	("20030057359" | "20030066311" | "20040159902" | "20050253213" | "20050253213" | "20050275048" | "4565928" | "5101099" | "5270571" | "5950074" | "6429036" | "6476469" | "6528875" | "6528875" | "6737292" | "6791660" | "6958261" | "6965107" | "7109580" | "7126210" | "7141782").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:19
L14	130	L13 not L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:27
L13	158	L12 and L6 and L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:27
L12	5925	(wafer near3 L2).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:27
L16	269667	(photoelectric (image adj1 sensor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:28
L19	499097	substrate.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:29
L18	30284	L16.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:29

L21	442	(L19 L12) and L6 and L18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:30
L23	95	(wafer and L2 and L16).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:33
L22	18	(US-20060030074-$ or US-20050266601-$ or US-20060033198-$ or US-20070166029-$ or US-20030056967-$ or US-20030049925-$).did. or (US-5895233-$ or US-7029960-$ or US-6204506-$ or US-7229900-$ or US-5986736-$ or US-7180197-$ or US-7071488-$ or US-6624921-$ or US-6461890-$ or US-5965064-$ or US-6526653-$ or US-6483030-$).did.	US-PGPUB; USPAT	OR	ON	2008/08/03 18:33
L25	11607	((438/118-119,455-456,459,977,690-693,700,959) or (257/E21.237,E21.484)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/03 18:35
L26	11	("20040137723" | "20040232104" | "20060030074" | "20060043555" | "4565928" | "5101099").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:38

8/3/2008 6:41:01 PM
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